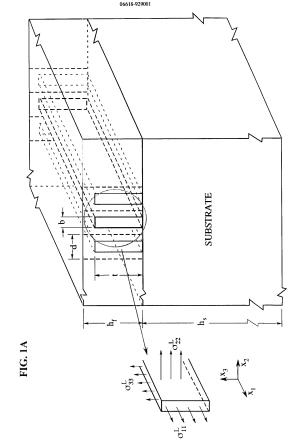
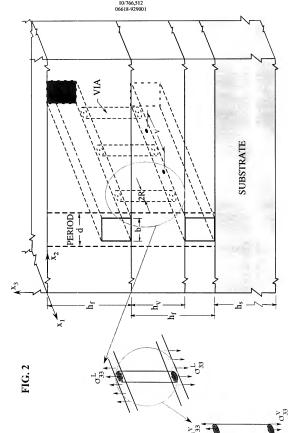
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10766.512
06618-929001

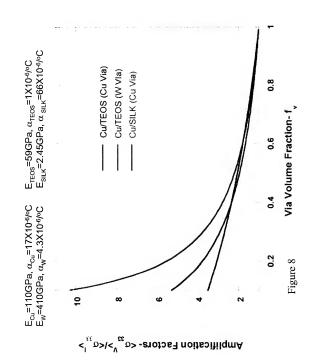


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FIG. 1B

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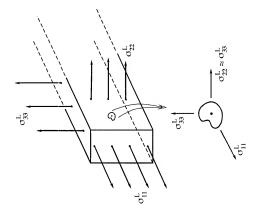


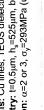


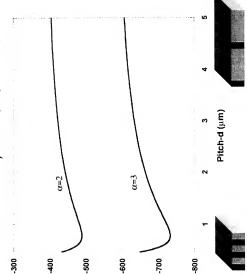
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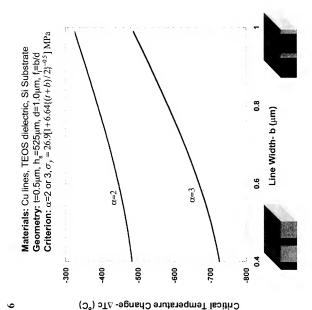




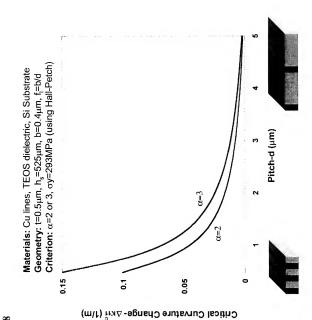


Critical Temperature Change- △Tc (°C)

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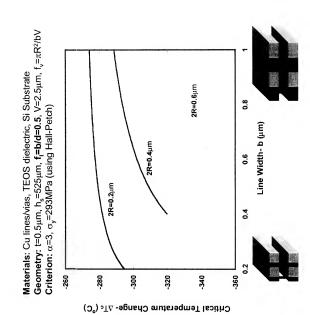


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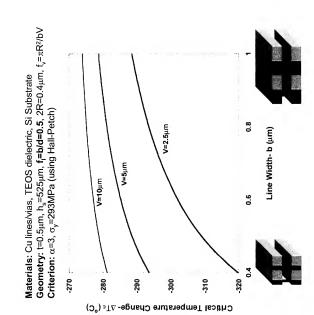
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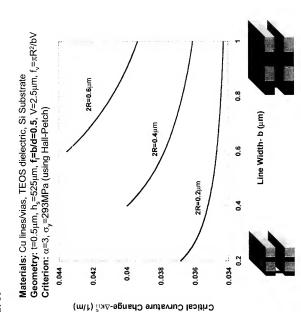
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FIG. 11

Materials: Cu lines/vias, TEOS dielectric, Si Substrate

